



Low-Cost High-Speed, IC Operational Amplifier

AD518

1.1 Scope.

This specification covers the detail requirements for a high-speed precision monolithic op amp with a high slew rate and wide bandwidth using feed forward circuitry.

1.2 Part Number.

The complete part number per Table 1 of this specification is as follows:

Device **Part Number**
-1 AD518SH/883E

1.2.3 Case Outline.

See Appendix 1 of General Specification ADI-M-1000: package outline: HO8A

1.3 Absolute Maximum Ratings. ($T_A = +25^\circ\text{C}$ unless otherwise noted)

NOTES

¹Maximum package power dissipation vs. ambient temperature.

Package Type	MAXIMUM AMBIENT Temperature for Rating	DERATE ABOVE MAXIMUM Ambient Temperature
TO-92	80°C	7.1 mW/°C

²The inputs are shunted with back to back diodes; if the V_{DIFF} is greater than $\pm 1V$, a resistor should be used in series with the inputs to limit the current to $\pm 10mA$.

1.5 Thermal Characteristics

Thermal Resistance $\theta_{jc} = 65^\circ\text{C/W}$
 $\theta_{ja} = 150^\circ\text{C/W}$

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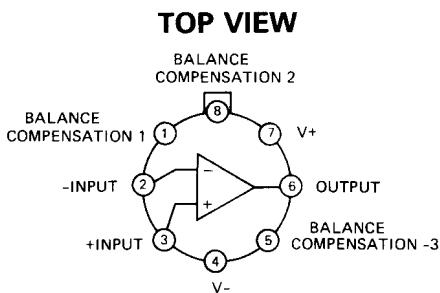
Test	Symbol	Device	Design Limit @ + 25°C	Sub Group 1	Sub Group 2, 3	Sub Group 4	Test Condition ¹	Units
Gain Open Loop	A _{OL}	- 1	50		25	50	R _L ≥ 2 kΩ ΔV _O = 10 V	V/mV min
Gain Bandwidth Product	GBW	- 1	10					MHz min
Slew Rate, Unity Gain	t _{SR}	- 1	50					V/μs min
Output Voltage Swing	V _{OUT}	- 1	12	12	12		R _L = 2 kΩ	± V min
Output Short Circuit Current	I _{SC}	- 1	25	65				± mA max
Input Offset Voltage Drift	TCV _{IO}	- 1	20		20		R _S = 100 Ω	± μV/°C max
Input Offset Voltage	V _{IO}	- 1	4	4	6		R _S = 100 Ω	± mV max
Input Offset Current	I _{OS}	- 1	50	50	100			± nA max
Input Bias Current	I _B	- 1	250	250	400			± nA max
Common-Mode Rejection	CMRR	- 1	80		80	80		dB min
Common-Mode Voltage Range	CMVR	- 1	10	10				± V max
Power Supply Current	I _Q	- 1	7	7				mA max
Power Supply Rejection Ratio	PSRR	- 1	100		150	100		μV/V max

NOTE

¹T_A = + 25°C and V_S = ± 15 V dc unless otherwise specified.

Table 1.

3.2.1 Functional Block Diagram and Terminal Assignments.

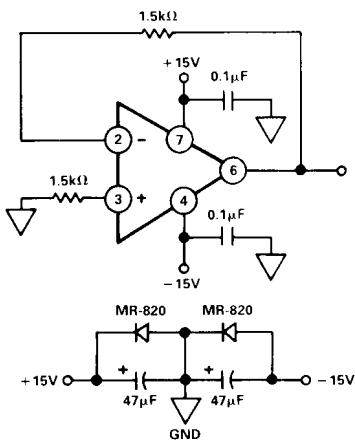


3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (49).

4.2.1 Life Test/Burn-In Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).



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